

DS26C32AMQML Quad Differential Line Receiver

Check for Samples: DS26C32AMQML

FEATURES

- CMOS Design for Low Power
- ±0.2V Sensitivity Over Input Common Mode Voltage Range
- Input Fail-Safe Circuitry
- Inputs Won't Load Line When $V_{CC} = 0V$
- Meets the Requirements of EIA Standard RS-422
- **TRI-STATE Outputs for Connection to System Buses**

DESCRIPTION

The DS26C32A is a guad differential line receiver designed to meet the RS-422, RS-423, and Federal Standards 1020 and 1030 for balanced and unbalanced digital data transmission, while retaining the low power characteristics of CMOS.

The DS26C32A has an input sensitivity of 200 mV over the common mode input voltage range of ±7V. The DS26C32A features internal pull-up and pulldown resistors which prevent output oscillation on unused channels.

The DS26C32A provides an enable and disable function common to all four receivers, and features TRI-STATE outputs with 6 mA source and sink capability. This product is pin compatible with the DS26LS32A and the AM26LS32.

CONNECTION DIAGRAMS

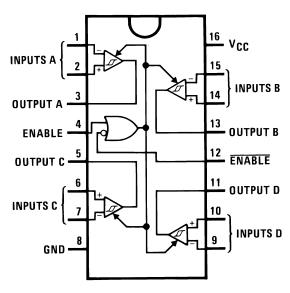


Figure 1. CDIP and CLGA Packages-Top View See Package Numbers NFE0016A, NAC0016A, or NAD0016A

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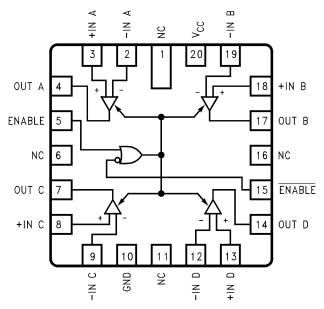


Figure 2. 20-Lead LCCC Package-Top View See Package Number NAJ0020A

Logic Diagram ENABLE ENABLE IN D2 IN D1 IN C2 IN C1 IN B2 IN B1 IN A2 IN A1 GND OUTPUT D OUTPUT C **OUTPUT B OUTPUT A** Vcc

Truth Table (1)

ENABLE	ENABLE	Input	Output
L	Н	X	Z
	Other	V _{ID} ≥ V _{Th} (Max)	Н
Combinations of Enable Inputs		V _{ID} ≤ V _{Th} (Min)	L
		Open	Н

(1) Z = TRI-STATE



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

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Absolute Maximum Ratings(1)(2)

Supply Voltage (V _{CC})	7V
Common Mode Range (V _{CM})	±14V
Differential Input Voltage (V _{Diff})	±14V
Enable Input Voltage (V _I)	7V
Storage Temperature Range (T Stg)	-65°C ≤ T _A ≤ +150°C
Lead Temperature (Soldering 4 sec.)	260°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not verify specific performance limits. For verified specifications and test conditions, see the Electrical Characteristics. The verified specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) Unless otherwise specified, all voltages are referenced to ground.

Recommended Operating Conditions

	Min	Max	Units
Supply Voltage (V _{CC})	4.50	5.50	V
Operating Temperature Range (T _A)	- 55	+125	°

Quality Conformance Inspection

Table 1. Mil-Std-883, Method 5005 - Group A

Subgroup	Description	Temp °C
1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	Functional tests at	+25
8A	Functional tests at	+125
8B	Functional tests at	-55
9	Switching tests at	+25
10	Switching tests at	+125
11	Switching tests at	-55
12	Settling time at	+25
13	Settling time at	+125
14	Settling time at	-55

DS26C32AM Electrical Characteristics DC Parameters

Parameter		Test Conditions	Notes	Min	Max	Unit	Sub- groups	
V _{TH} Minimum Differential Input Voltage		$V_{CC} = 5V, V_{O} = V_{OH} \text{ or } V_{OL},$ -7 < $V_{CM} < +7$		-200	+200	mV	1, 2, 3	
R _I	Input Resistance	V _{CC} = 5V, -7 < V _{CM} < +7, One input AC Gnd		4.5	11	ΚΩ	1, 2, 3	
II	Input Current	V _{CC} = 5V, V _I = +10V, Other Input = Gnd			+1.8	mA	1, 2, 3	
		$V_{CC} = 5V$, $V_I = -10V$, Other Input = Gnd			-2.7	mA	1, 2, 3	
V _{OH}	Logical "1" Output Voltage	$V_{CC} = 4.5V, V_{Diff} = +1V, I_{O} = -6.0mA$		3.8		V	1, 2, 3	
V _{OL}	Logical "0" Output Voltage	$V_{CC} = 5.5V, V_{CC} = Max, V_{Diff} = -1V, I_{O} = 6.0mA$			0.3	V	1, 2, 3	

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DS26C32AM Electrical Characteristics DC Parameters (continued)

Parameter		Test Conditions	Notes	Min	Max	Unit	Sub- groups
V _{IH}	Minimum Enable High Level Voltage		(1)	2.0		V	1, 2, 3
V _{IL}	Maximum Enable Low Level Voltage		(1)		0.8	V	1, 2, 3
l _{OZ}	Maximum TRI-STATE Output Leakage Current	V _O = V _{CC} or Gnd, Enable = V _{IL} , Enable = V _{IH}			±5.0	μΑ	1, 2, 3
I	Maximum Enable Input Current	$V_I = V_{CC}$ or Gnd			±1.0	μΑ	1, 2, 3
I _{CC}	Quiescent Power Supply Current	$V_{Diff} = +1V, V_{CC} = 5.5V$			25	mA	1, 2, 3

⁽¹⁾ Parameter tested Go-No-Go only.

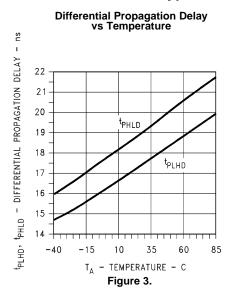
DS26C32AM Electrical Characteristics AC Parameters - Propagation Delay Time

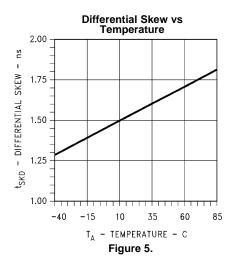
The following conditions apply, unless otherwise specified. $V_{CC} = 5V \pm 10\%$, $C_{CL} = 50pF$, $V_{Diff} = 2.5V$

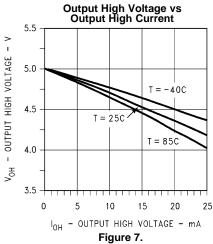
Parameter		Test Conditions	Notes	Min	Max	Unit	Sub- groups
t _{PLH}	Input to Output Prop Delay	$V_{CM} = 0V$			35	ns	9, 10, 11
t _{PHL}	Input to Output Prop Delay	$V_{CM} = 0V$			35	ns	9, 10, 11
t _{Rise}	Output Rise Time	V _{CM} = 0V			9	ns	9, 10, 11
t _{Fall}	Output Fall Time	V _{CM} = 0V			9	ns	9, 10, 11
t _{PLZ}	Output Disable Time	$R_L = 1000\Omega$			29	ns	9, 10, 11
t _{PZL}	Output Enable Time	$R_L = 1000\Omega$			29	ns	9, 10, 11
t _{PHZ}	Output Disable Time	$R_L = 1000\Omega$			29	ns	9, 10, 11
t _{PZH}	Output Enable Time	$R_L = 1000\Omega$			29	ns	9, 10, 11

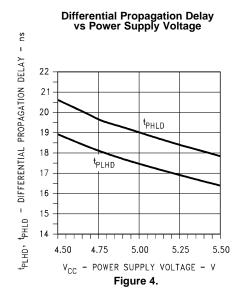


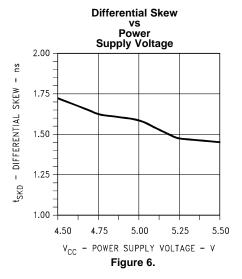
Typical Performance Characteristics

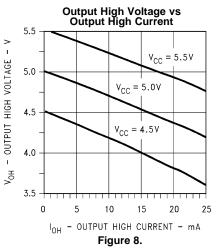






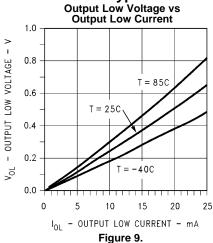


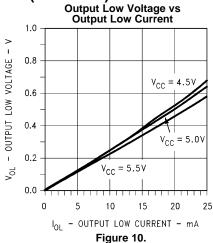


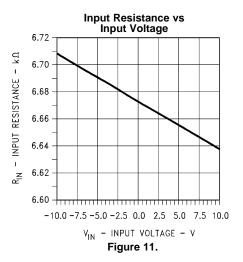


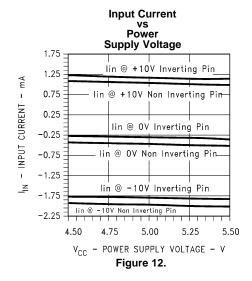


Typical Performance Characteristics (continued)

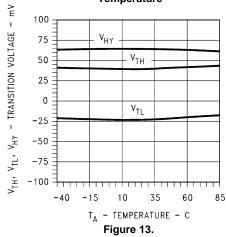




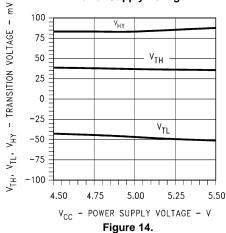






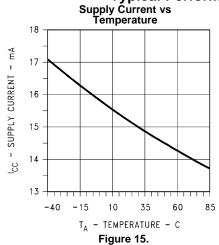


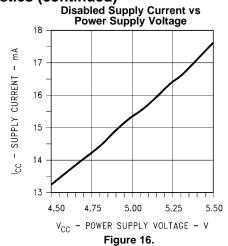
Hysteresis & Differential Transition Voltage vs Power Supply Voltage

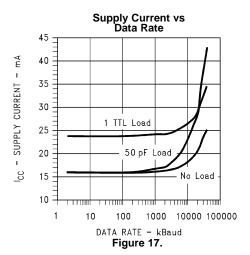




Typical Performance Characteristics (continued)

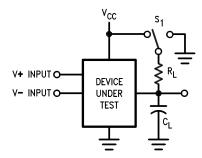








AC TEST CIRCUIT AND SWITCHING TIME WAVEFORMS



 C_{L} includes load and test jig capacitance.

 S_1 = V_{CC} for $_{tPZL},$ and t_{PLZ} measurements.

 S_1 = Gnd for t_{PZH} , and t_{PHZ} measurements.

Figure 18. Test Circuit for TRI-STATE Output Tests

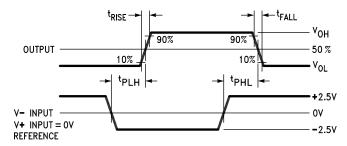


Figure 19. Propagation Delay

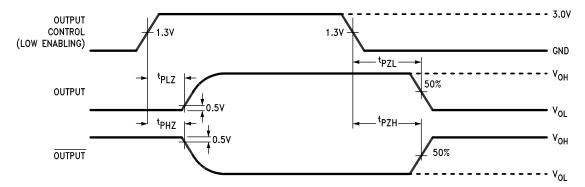
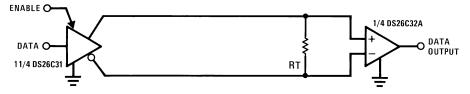


Figure 20. TRI-STATE Output Enable and Disable Waveforms

TYPICAL APPLICATIONS

Figure 21. Two-Wire Balanced Systems, RS-422



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REVISION HISTORY

Released	Revision	Section	Changes
10/26/2010	*	New Release, Corporate format	MDS data sheets converted into one Corp. data sheet format. MNDS26C32AM-X Rev 0B0 will be archived.
4/15/2013	Α		Changed layout of National Data Sheet to TI format





26-Mar-2016

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9164001M2A	ACTIVE	LCCC	NAJ	20	50	TBD	Call TI	Call TI	-55 to 125	DS26C32AME /883 Q 5962-91640 01M2A ACO 01M2A >T	Samples
5962-9164001MEA	ACTIVE	CDIP	NFE	16	25	TBD	Call TI	Call TI	-55 to 125	DS26C32AMJ/883 5962-9164001MEA Q	Samples
5962-9164001MFA	ACTIVE	CFP	NAD	16	19	TBD	Call TI	Call TI	-55 to 125	DS26C32AMW /883 Q 5962-91640 01MFA ACO 01MFA >T	Samples
5962-9164001MXA	ACTIVE	CFP	NAC	16	42	TBD	Call TI	Call TI	-55 to 125	DS26C32AMWG /883 Q 5962-91640 01MXA ACO 01MXA >T	Samples
DS26C32A MD8	ACTIVE	DIESALE	Y	0	100	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-55 to 125		Samples
DS26C32AME/883	ACTIVE	LCCC	NAJ	20	50	TBD	Call TI	Call TI	-55 to 125	DS26C32AME /883 Q 5962-91640 01M2A ACO 01M2A >T	Samples
DS26C32AMJ/883	ACTIVE	CDIP	NFE	16	25	TBD	Call TI	Call TI	-55 to 125	DS26C32AMJ/883 5962-9164001MEA Q	Samples
DS26C32AMW/883	ACTIVE	CFP	NAD	16	19	TBD	Call TI	Call TI	-55 to 125	DS26C32AMW /883 Q 5962-91640 01MFA ACO 01MFA >T	Samples
DS26C32AMWG/883	ACTIVE	CFP	NAC	16	42	TBD	Call TI	Call TI	-55 to 125	DS26C32AMWG /883 Q 5962-91640 01MXA ACO 01MXA >T	Samples



PACKAGE OPTION ADDENDUM

26-Mar-2016

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

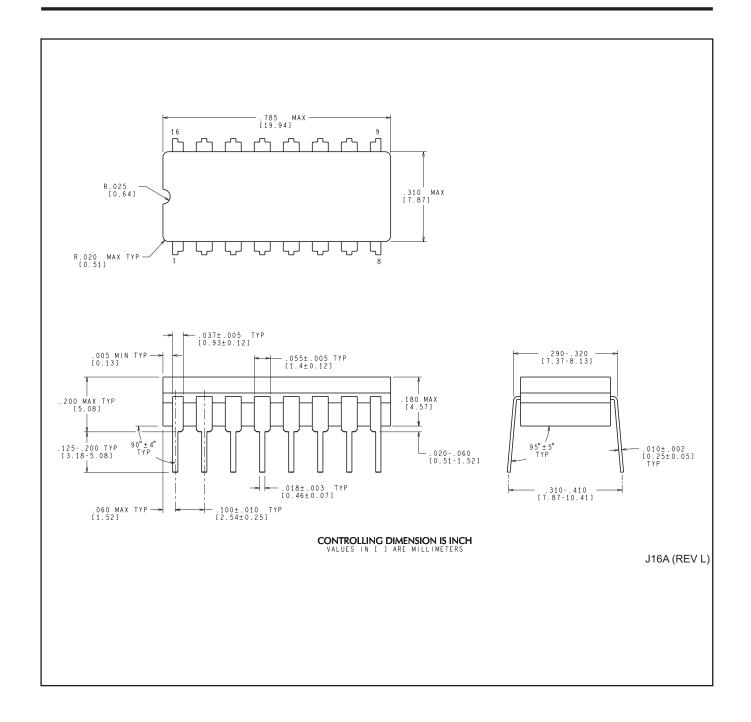
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

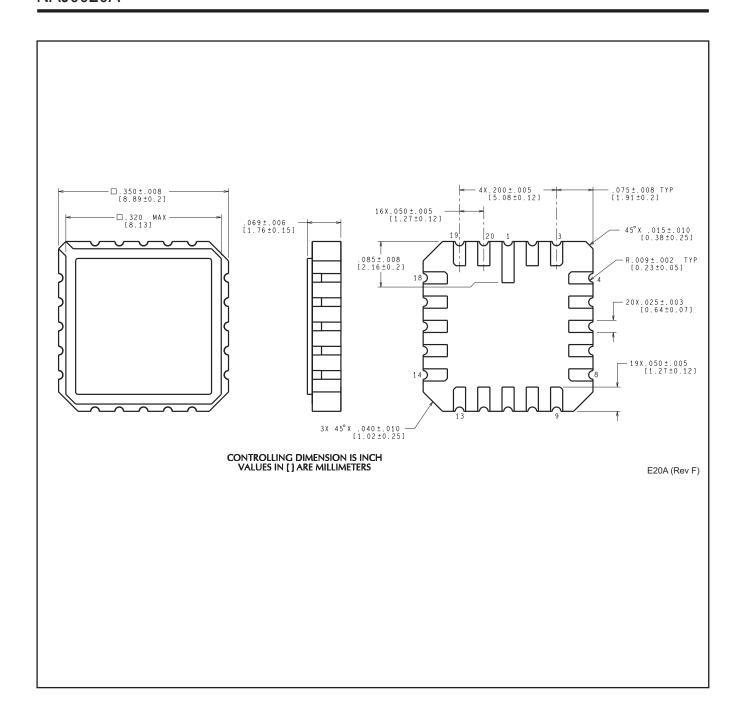
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

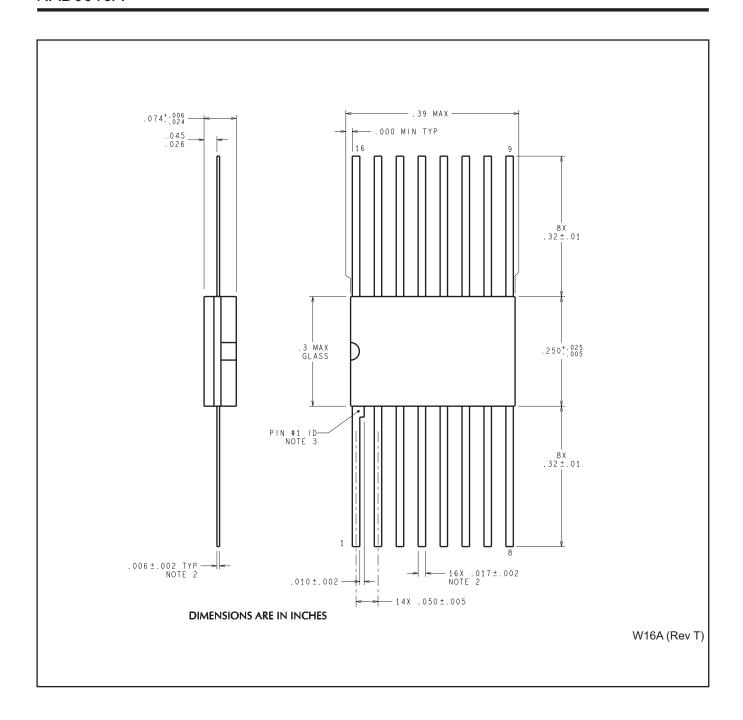
- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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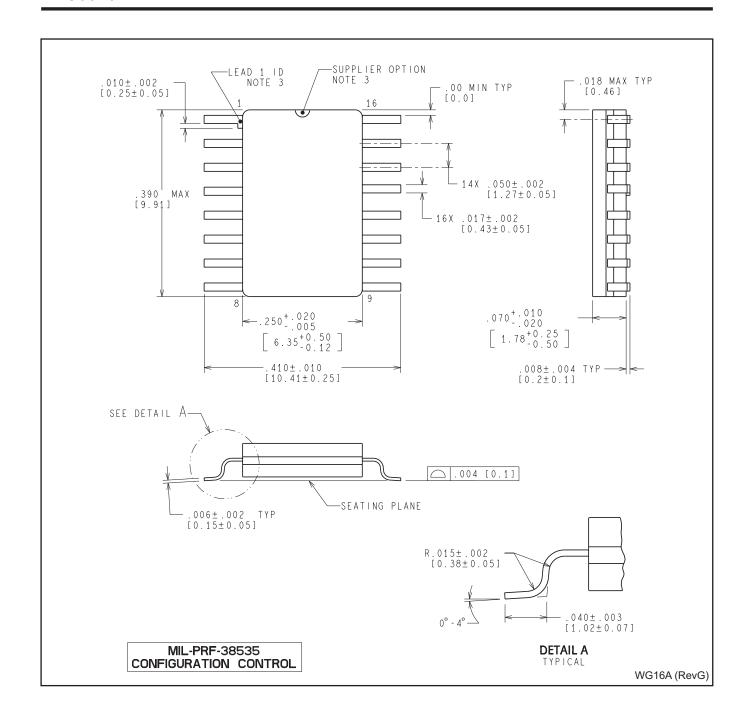
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